

# NEIWEN LING

Department of Computer Science, Yale University

Address: Arthur K. Watson Hall, 51 Prospect Street, New Haven, CT 06511, U.S.

Email: [neiwen.ling@yale.edu](mailto:neiwen.ling@yale.edu) ♦ Phone: (+1)(203)9965536 ♦ Homepage: <https://neawhen.github.io/neiwen.github.io/>

## RESEARCH INTERESTS

My primary research interests lie at the intersection of Edge Computing, Machine Learning, Cyber-Physical Systems (CPS), and Real-time Systems. I am committed to advancing **time-sensitive AI systems**, with a particular focus on designing AI (i.e, DL, FM, LLM) systems for **embodied agents** such as robots, assistive devices, and autonomous vehicles. These systems have wide-ranging applications, including **autonomous driving, embodied AI, and smart cities**. Additionally, I have extensive experience in developing real-world testbeds, including a campus-scale smart lamppost testbed.

- Systems for Large Language Model (LLM), Time-sensitive LLMs in CPS/IoT
- Systems for Embodied AI, On-device Deep Learning (DL), Time-sensitive DL
- Distributed DL Systems, Cooperative Edge Computing

## RESEARCH EXPERIENCE

<b>Yale University</b> Postdoctoral Associate, Efficient Computing Lab, Department of Computer Science Supervisor: <a href="#">Prof. Lin Zhong</a> Research Directions: Time-sensitive LLM Serving System, System for Embodied AI	10/2023-Present
<b>The Chinese University of Hong Kong</b> Postdoctoral Fellow, AIoT lab, Department of Information Engineering Research Directions: Distributed DL System, Foundation Model for IoT	08/2022-10/2023
<b>Shenzhen Institute of Artificial Intelligence and Robotics for Society</b> Visiting Ph.D. student	11/2019-01/2020

## EDUCATION

<b>The Chinese University of Hong Kong</b> Ph.D., Information Engineering Supervisor: <a href="#">Prof. Guoliang Xing</a> Research Directions: DL on CPU-GPU heterogeneous platforms, Edge Computing	08/2018-07/2022
<b>Northwestern Polytechnical University</b> Bachelor's Degree, Electronics and Information Engineering	09/2014-07/2018

## HONORS & AWARDS

• Best Artifact Award Runner-Up, ACM MobiCom	2024
• Best Paper Award Finalist, ACM SenSys	2022
• Best Poster Award, ACM SenSys	2022
• N2Women Young Researcher Fellowship, ACM SenSys	2021
• Postgraduate Scholarship, The Chinese University of Hong Kong	2018-2022
• Undergraduate Excellent Graduation Project, Northwestern Polytechnical University	2018

## PUBLICATIONS

### Conference Papers

- [Neiwen Ling](#), Xuan Huang, Zhihe Zhao, Nan Guan, Zhenyu Yan, and Guoliang Xing, "BlastNet: Exploiting Duo-Blocks for Cross-Processor Real-Time DNN Inference", The 20th Conference on Embedded Networked Sensor Systems, 15 pages double column  
**ACM SenSys 2022, Best Paper Award Finalist**
- [Neiwen Ling](#), Kai Wang, Yuze He, Guoliang Xing, and Daqi Xie, "RT-mDL: Supporting real-time mixed deep learning tasks on edge platforms", The 19th Conference on Embedded Networked Sensor Systems, 14 pages double column  
**ACM SenSys 2021**

- Shuyao Shi\*, Neiwen Ling\*, Zhehao Jiang\*, Xuan Huang\*, Yuze He, Xiaoguang Zhao, Bufang Yang, Chen Bian, Jingfei Xia, Zhenyu Yan, Raymond Yeung, and Guoliang Xing, "Soar: Design and Deployment of A Smart Roadside Infrastructure System for Autonomous Driving", The 30th Annual International Conference On Mobile Computing And Networking, 16 pages double column  
**ACM MobiCom 2024, Best Artifact Award Runner-Up**
- Zhehao Jiang\*, Neiwen Ling\*, Xuan Huang, Shuyao Shi, Chenhao Wu, Xiaoguang Zhao, Zhenyu Yan, and Guoliang Xing, "CoEdge: A Cooperative Edge System for Distributed Real-Time Deep Learning Tasks", The 22nd ACM/IEEE Conference on Information Processing in Sensor Networks, 14 pages double column  
**ACM/IEEE IPSN 2023**
- Zhihe Zhao, Neiwen Ling, Nan Guan, and Guoliang Xing, "Miriam: Exploiting Elastic Kernels for Real-time Multi-DNN Inference on Edge GPU", the 21th Conference on Embedded Networked Sensor Systems, 14 pages double column  
**ACM SenSys 2023**
- Bufang Yang, Lixing He, Neiwen Ling, Zhenyu Yan, Guoliang Xing, Xian Shuai, Xiaozhe Ren and Xin Jiang, "EdgeFM: Leveraging Foundation Model for Open-set Learning on the Edge", the 21th Conference on Embedded Networked Sensor Systems, 14 pages double column  
**ACM SenSys 2023**
- Zhihe Zhao, Kai Wang, Neiwen Ling, and Guoliang Xing, "Edgeml: An automl framework for real-time deep learning on the edge", The 6th ACM/IEEE Conference on Internet of Things Design and Implementation, 12 pages double column  
**ACM/IEEE IoTDI 2021**
- Xiaomin Ouyang, Zhiyuan Xie, Heming Fu, Sitong Cheng, Li Pan, Neiwen Ling, Guoliang Xing, Jiayu Zhou, and Jianwei Huang, "Harmony: Heterogeneous Multi-Modal Federated Learning through Disentangled Model Training", The 21st ACM International Conference on Mobile Systems, Applications, and Services, 14 pages double column  
**ACM MobiSys 2023**
- Wenjing Xie, Tao Hu, Neiwen Ling, Guoliang Xing, Chun Jason Xue, and Nan Guan, "Timely Fusion of Surround Radar/Lidar for Object Detection in Autonomous Driving Systems", the 30th IEEE International Conference on Embedded and Real-Time Computing Systems and Application, 6 pages double column  
**IEEE RTCSA 2024**

#### Workshop and Poster/Demo Papers

- Neiwen Ling\*, Yuze He\*, Nan Guan, Heming Fu, and Guoliang Xing, "Dataset: An Indoor Smart Traffic Dataset and Data Collection System", The 5th International SenSys/BuildSys Workshop on Data  
**ACM DATA 2022, SenSys/BuildSys 2022 Workshop**
- Zhihe Zhao, Xian Shuai, Neiwen Ling, Nan Guan, Zhenyu Yan, and Guoliang Xing, "Moses: Exploiting Cross-device Transferable Features for On-device Tensor Program Optimization", The 24th International Workshop on Mobile Computing Systems and Applications 2023  
**ACM HotMobile 2023**
- Zhihe Zhao, Neiwen Ling, Nan Guan, and Guoliang Xing, "Aaron: Compile-time Kernel Adaptation for Multi-DNN Inference Acceleration on Edge GPU", The 20th Conference on Embedded Networked Sensor Systems  
**ACM SenSys 2022 Poster, Best Poster Award**
- Zhihe Zhao, Neiwen Ling, Kaiwei Liu, Nan Guan, and Guoliang Xing, "Unifying On-device Tensor Program Optimization through Large Foundation Model", The 21th Conference on Embedded Networked Sensor Systems, 2 pages double column  
**ACM SenSys 2023 Poster**

#### PROFESSIONAL SERVICES

- **Organizing Committee Member**
  - General Co-Chair, International Workshop on Foundation Models for Cyber-Physical Systems & Internet of Things (FMSys'25), in Cyber-Physical Systems and Internet-of-Things Week 2025 (CPS-IoT Week 2025)
  - Technical Program Committee Co-Chair, International Workshop on Foundation Models for Cyber-Physical Systems & Internet of Things (FMSys'24), in Cyber-Physical Systems and Internet-of-Things Week 2024 (CPS-IoT Week 2024)

---

<sup>1</sup>\* Equal contribution

- Organizer, N2Women (Networking Networking Women) Meeting in the 19th ACM Conference on Embedded Networked Sensor Systems (SenSys 2021)

- **Technical Program Committee Member**

- The 23rd ACM Conference on Embedded Networked Sensor Systems (ACM SenSys 2025)
- The 30th International Conference on Parallel and Distributed Systems (IEEE ICPADS 2024)
- Artifact Evaluation, The 30th Annual International Conference on Mobile Computing and Networking (ACM MobiCom 2024)
- The 8th IEEE/ACM Conference on Connected Health: Applications, Systems, and Engineering Technologies (IEEE/ACM CHASE 2023)
- Poster & Demo, The 8th ACM/IEEE International Conference on Internet of Things Design and Implementation 2023 (IEEE/ACM IoTDI 2023)

- **Invited Reviewer**

- IEEE Transactions on Mobile Computing (TMC 2022, 2023, 2024)
- ACM Transactions on Sensor Networks (TOSN 2023, 2024)
- ACM Transactions on Internet of Things (TIOT 2023, 2024)
- SCIENCE CHINA Information Sciences (SCIS 2023)
- IEEE Network Magazine 2023
- ACM Transactions on Computing for Healthcare (HEALTH 2023)
- IEEE Transactions on Computers 2024
- Proceedings of the ACM on Interactive, Mobile, Wearable and Ubiquitous Technologies (IMWUT/UbiComp 2022)
- IEEE International Conference on Computer Communications (INFOCOM 2024)
- The First Workshop on DL-Hardware Co-Design for AI Acceleration in the 37th AAAI Conference on Artificial Intelligence (DCAA 2023)